

FIG. 1

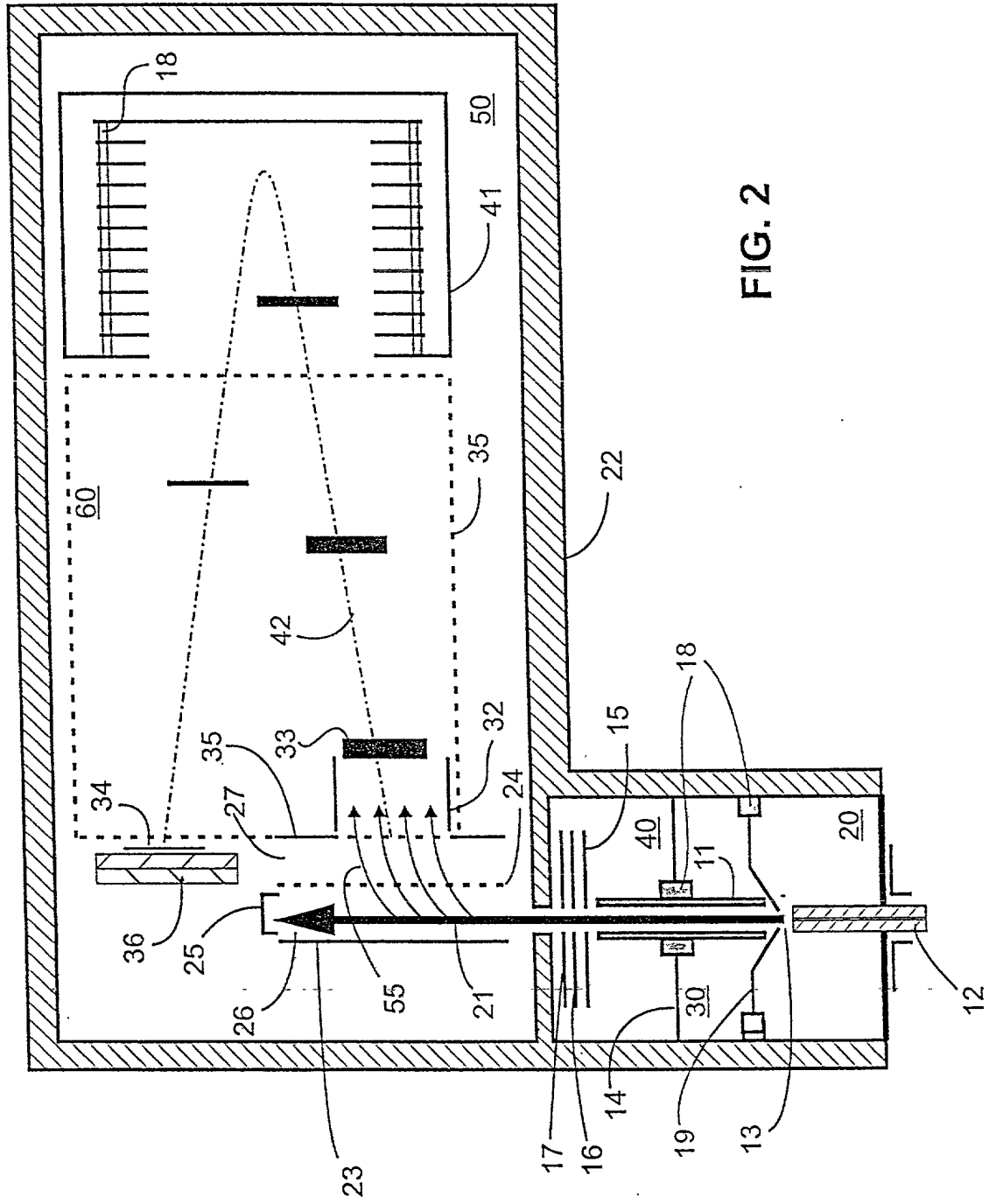


FIG. 2

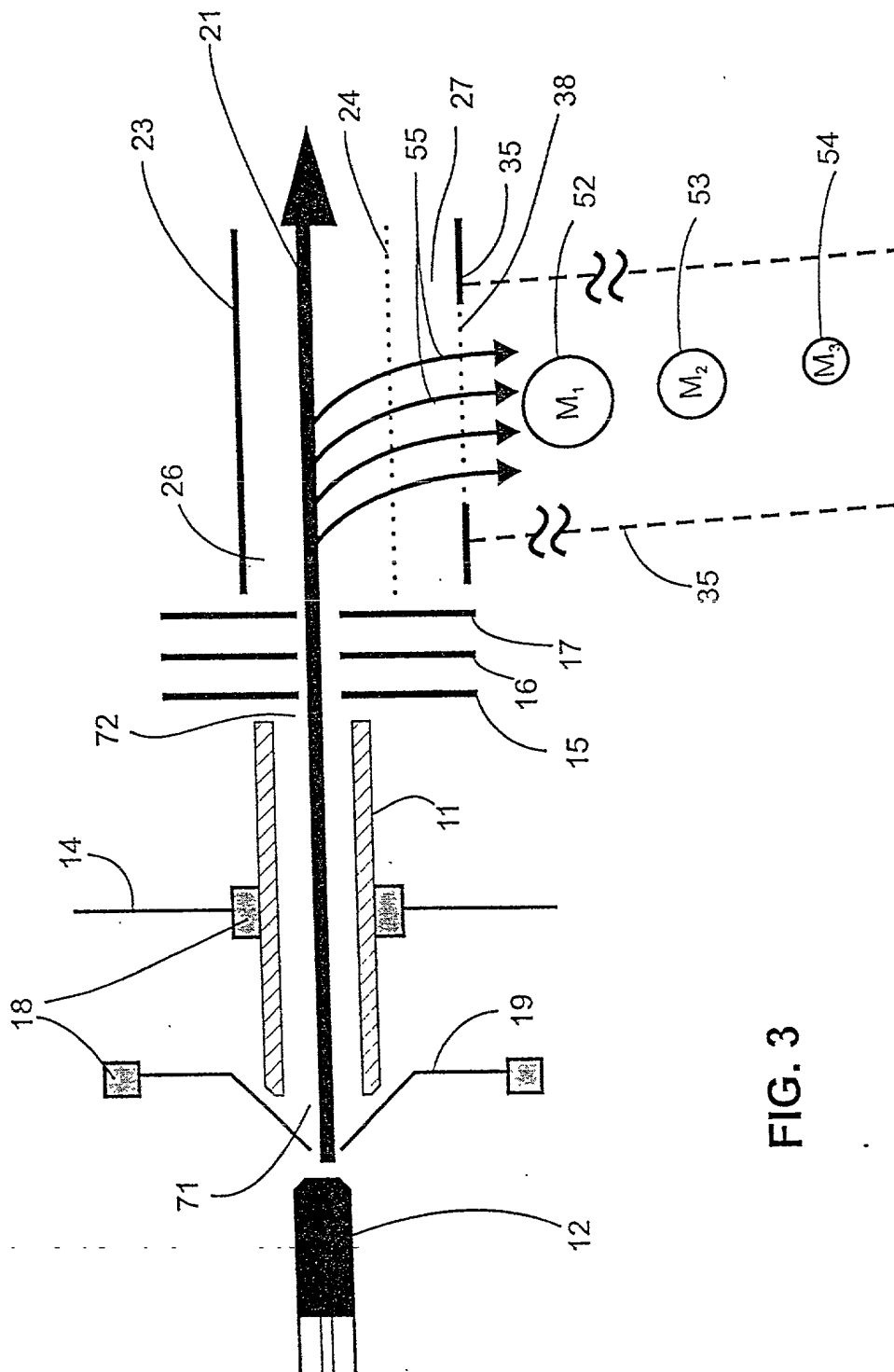


FIG. 3

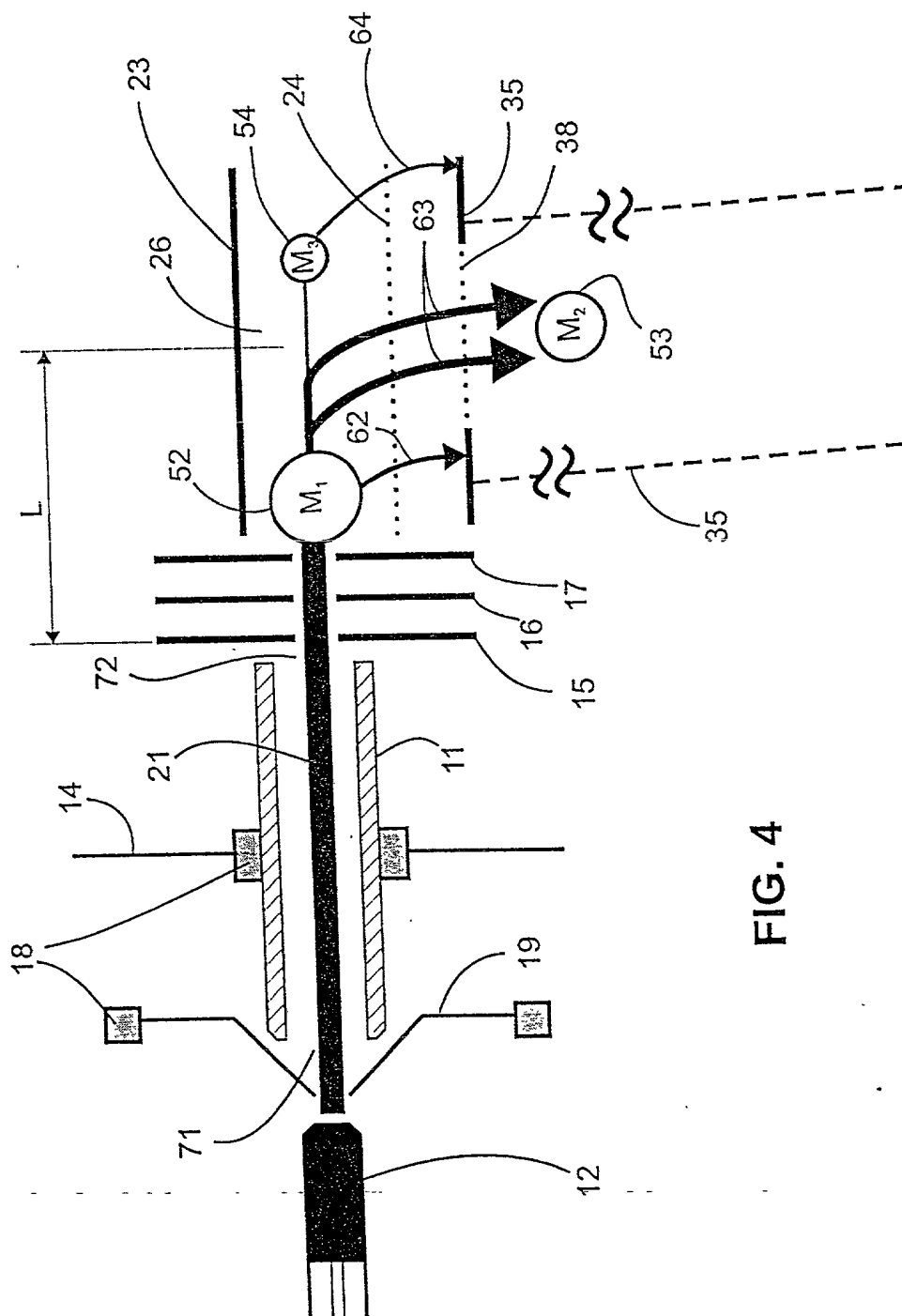


FIG. 4

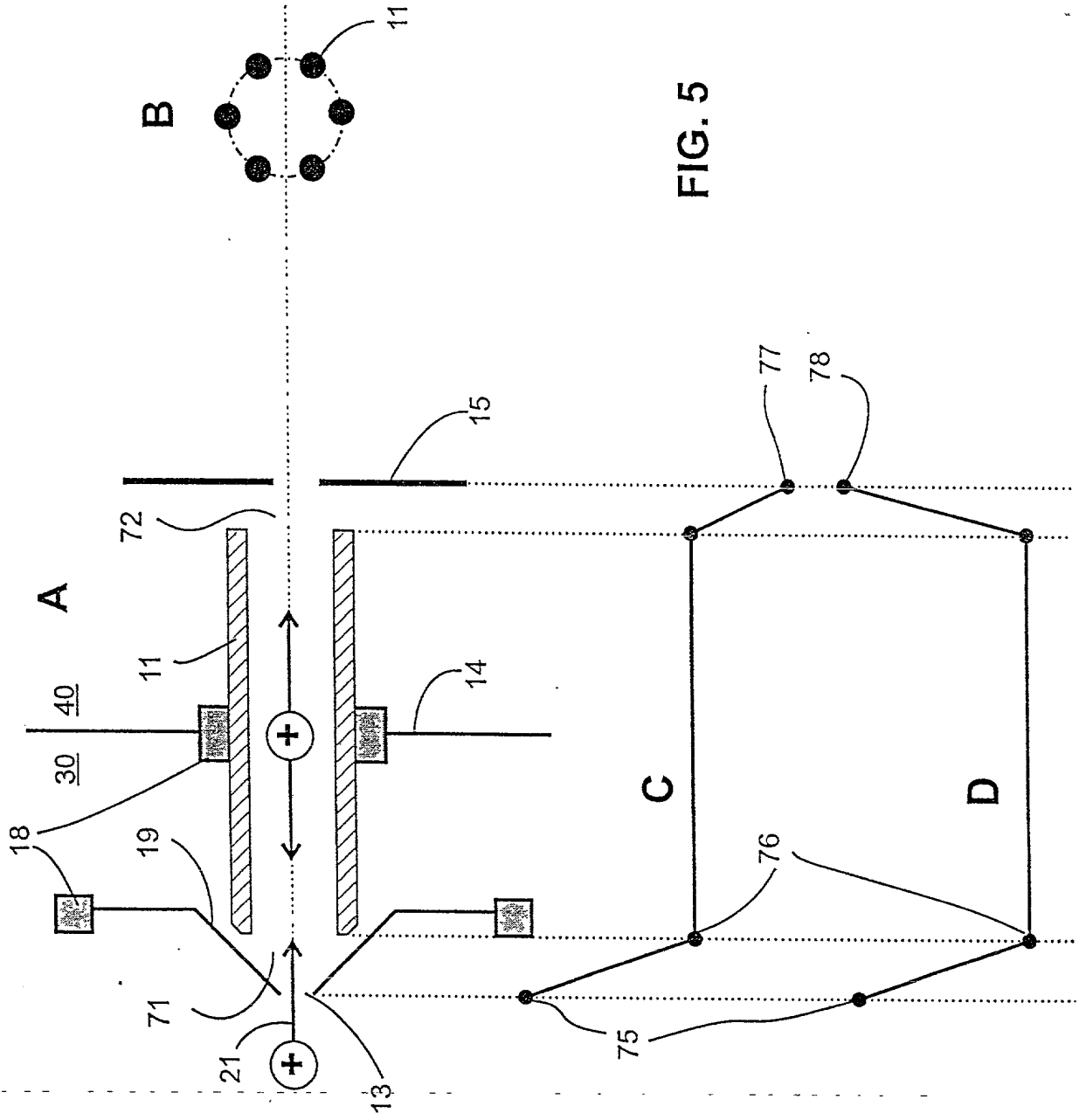
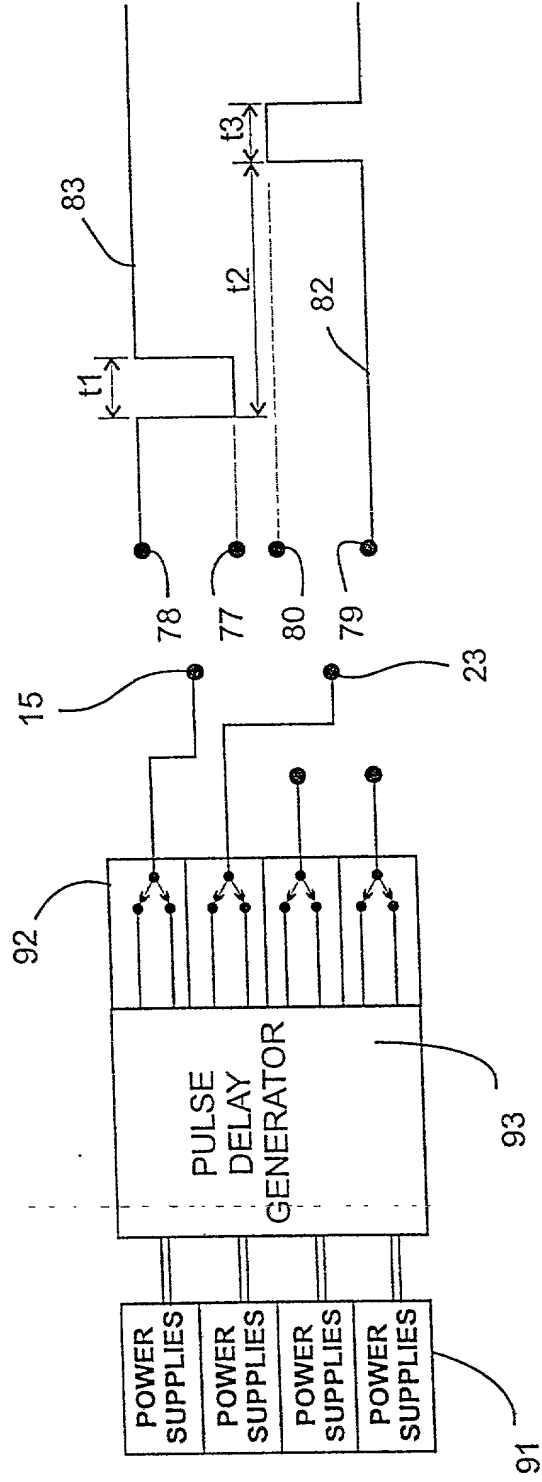


FIG. 5



**Fig. 6**

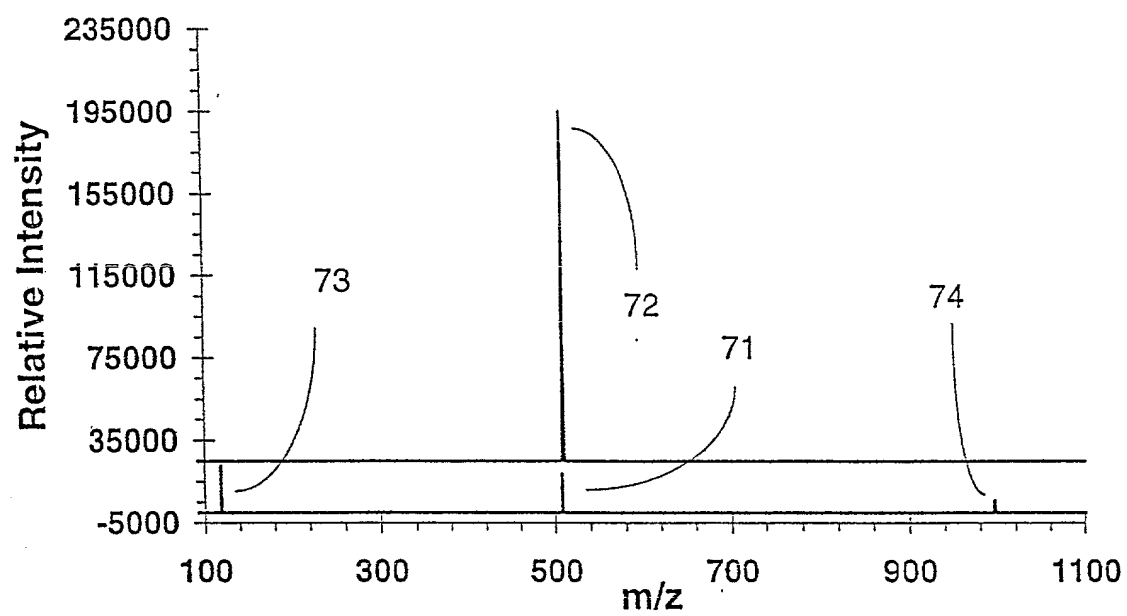


FIG. 7A

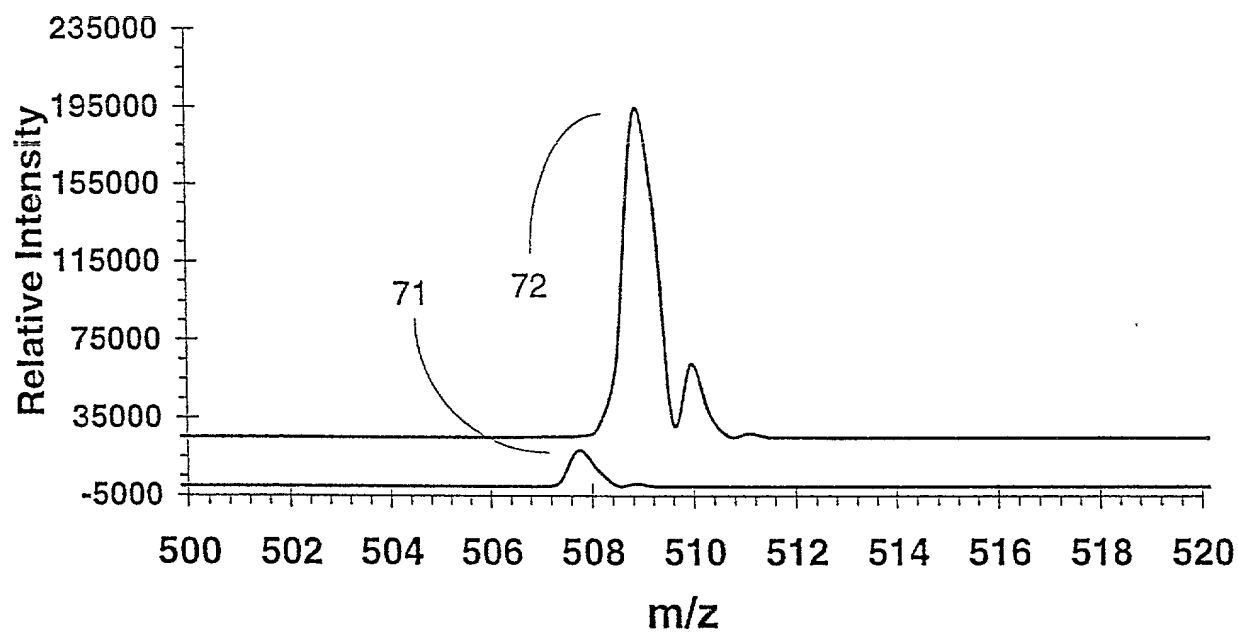


FIG. 7B



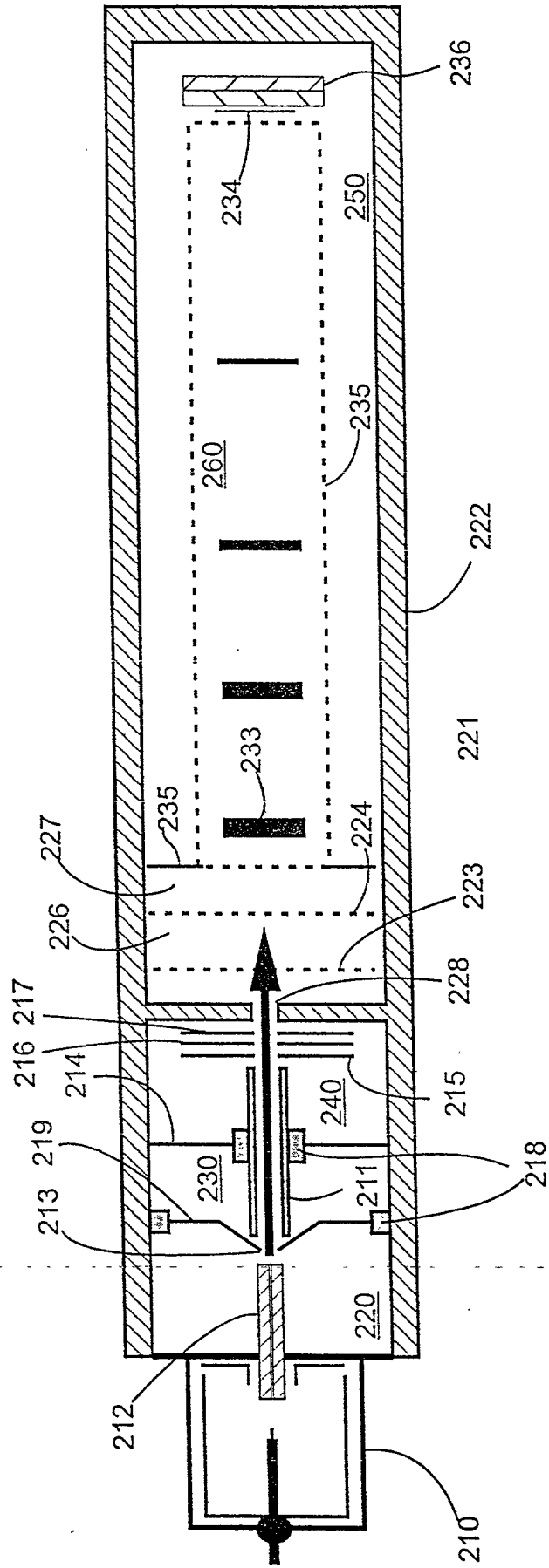
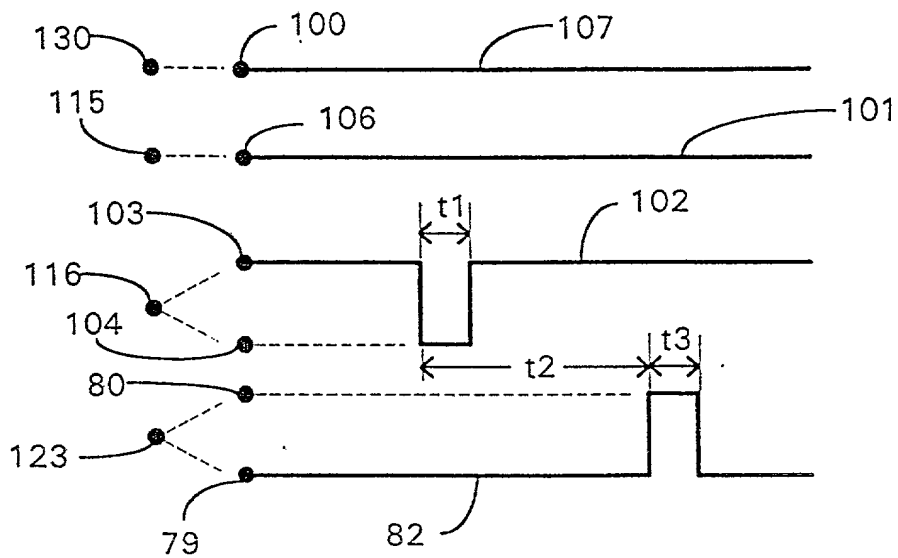
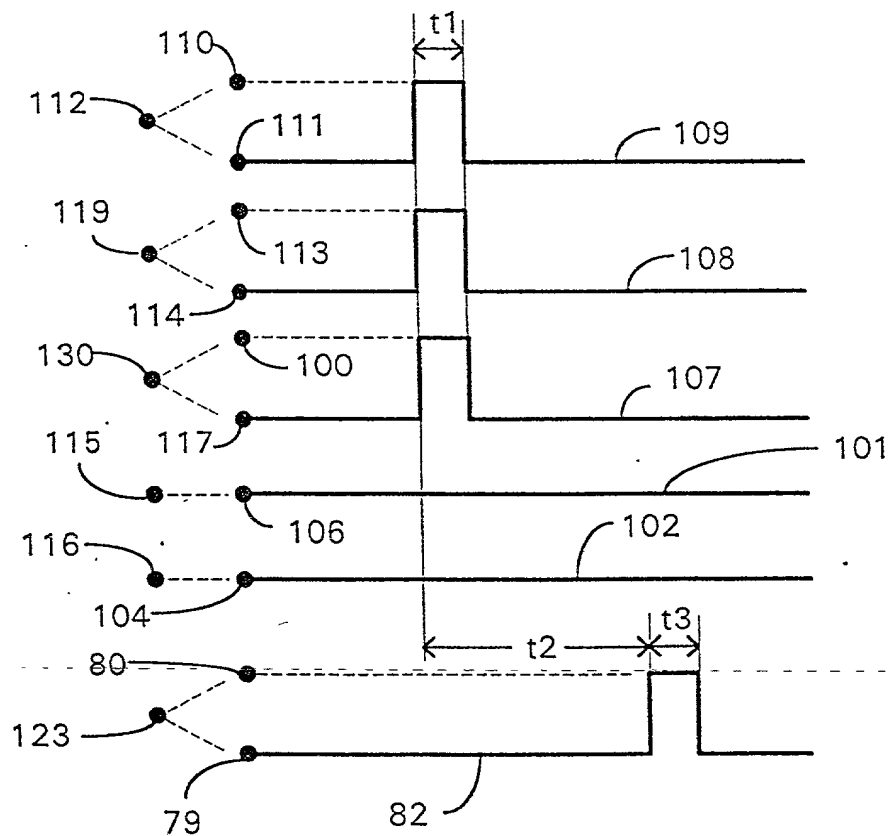


FIG. 8



A

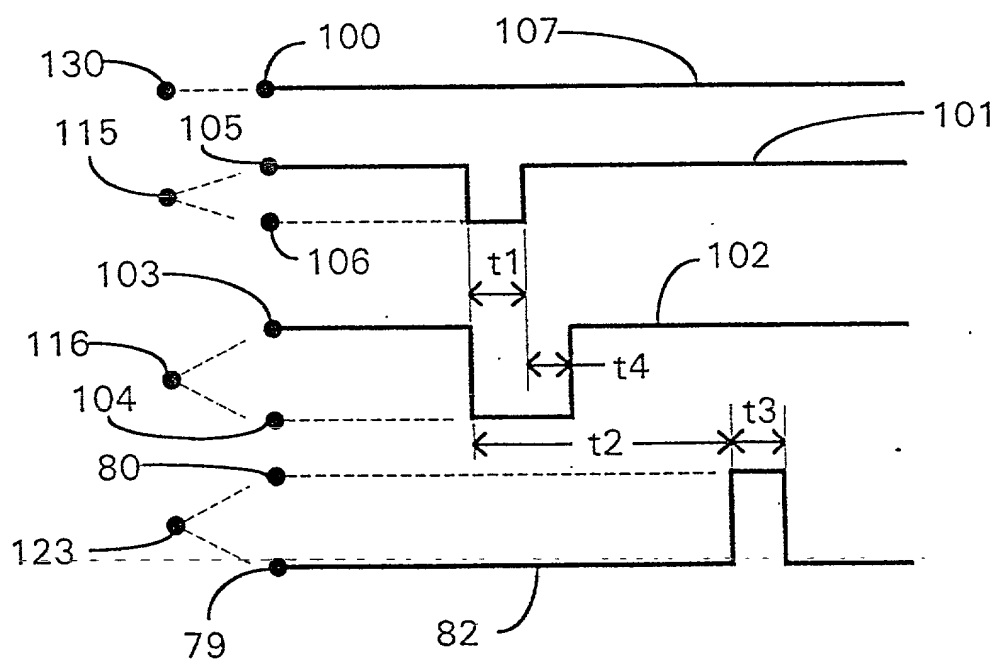


B

FIG. 9

This diagram shows a cross-sectional view of a semiconductor device. It features a central trench structure. The top layer is labeled 107. Below it is a layer 101. A layer 102 is located on the right side of the trench. The trench itself is defined by a bottom layer 82 and side walls 79. Various other layers and features are labeled with numbers: 130, 115, 105, 103, 116, 104, 80, 123, 100, 106, and 101. Dimensions  $t_1$ ,  $t_2$ , and  $t_3$  are indicated with arrows, representing the width of the trench, the distance from the trench edge to a feature, and the width of a feature, respectively.

A



# B

FIG. 10

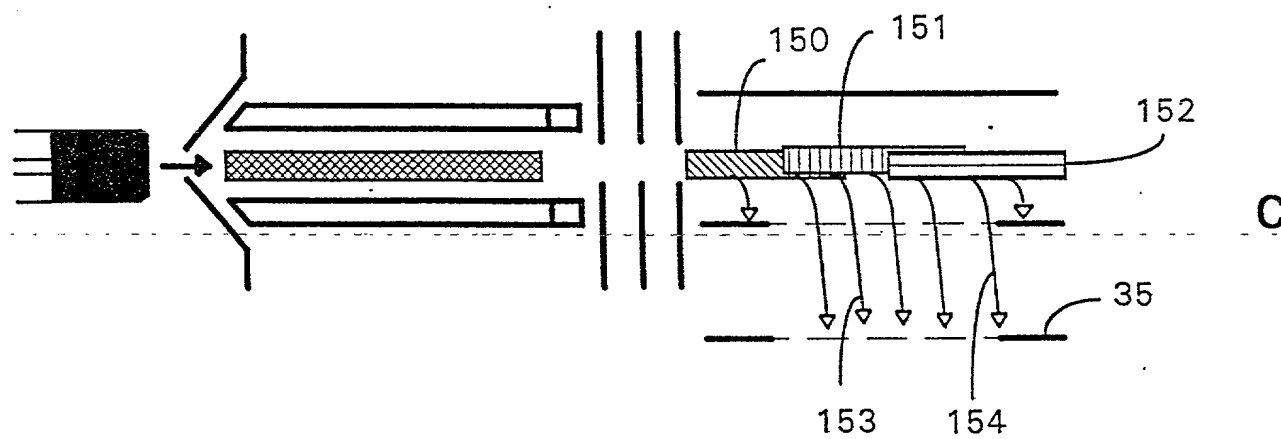
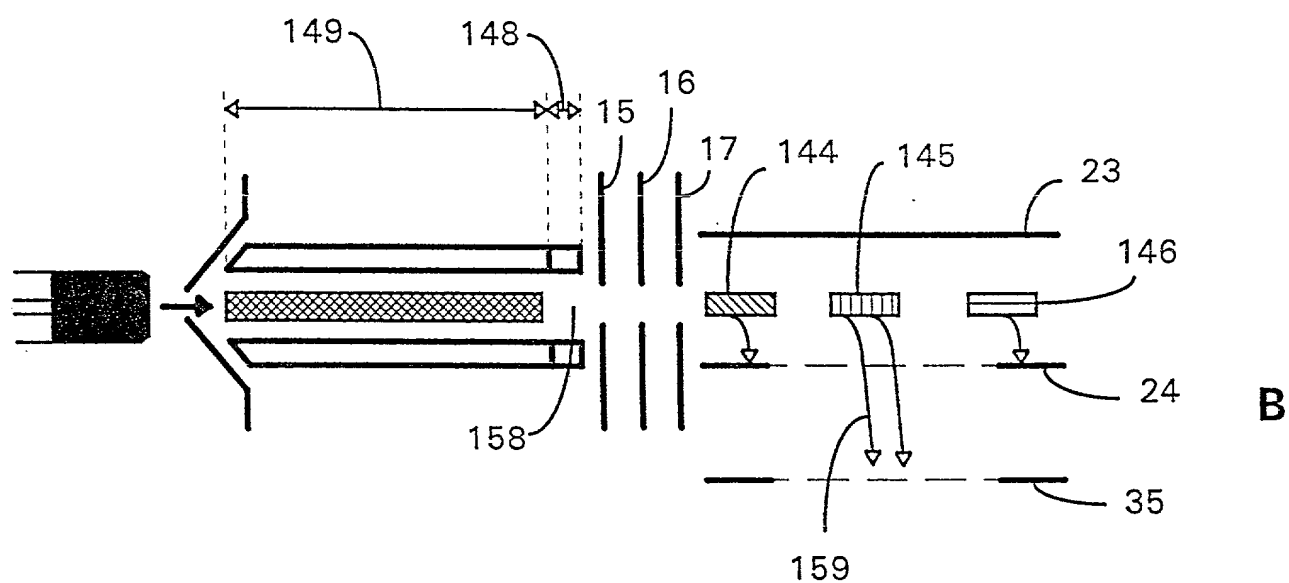
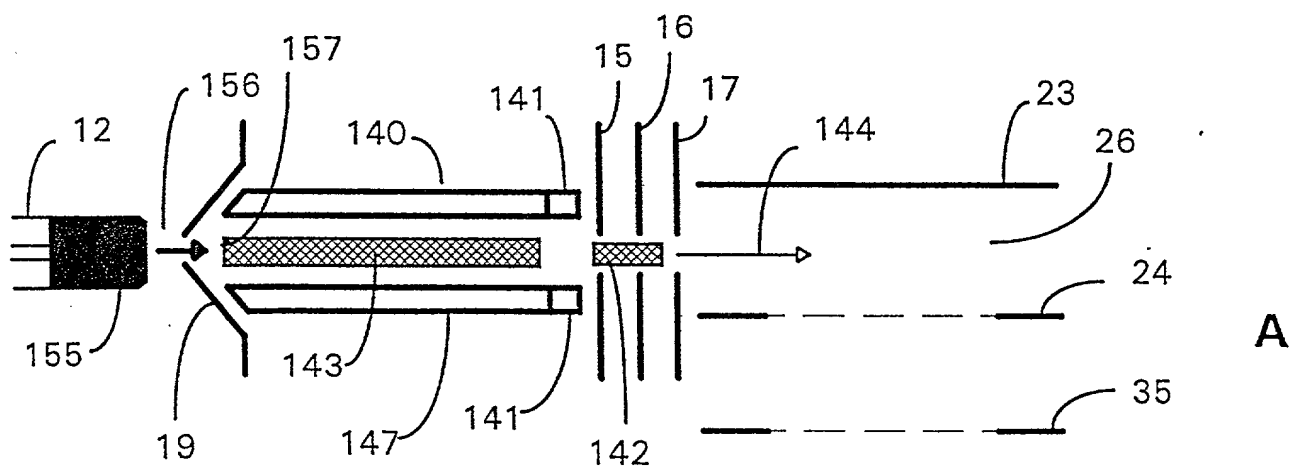


FIG. 11

Figure 1 is a schematic diagram of a multi-layer printed circuit board (PCB) showing various layers and components. The diagram includes layers 100, 102, 106, 107, 108, and 109. Components 110, 112, 113, 115, 116, 119, 123, 130, 160, 161, 162, 79, 80, 82, and 101 are shown. Time intervals  $t_1$ ,  $t_2$ , and  $t_3$  are indicated. A vertical line separates the left and right sides of the diagram.

FIG. 12